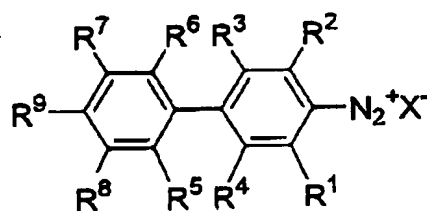


ABSTRACT OF THE DISCLOSURE

A heat-sensitive recording material includes, on a support thereof, a heat-sensitive recording layer containing a diazo compound and a coupler. The diazo compound is encapsulated in microcapsules and is represented by the following general formula (1):

General formula (1)



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